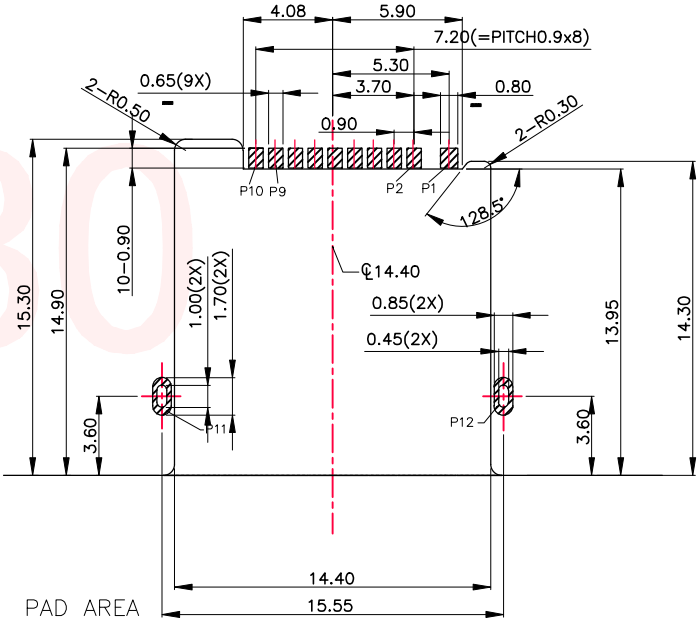
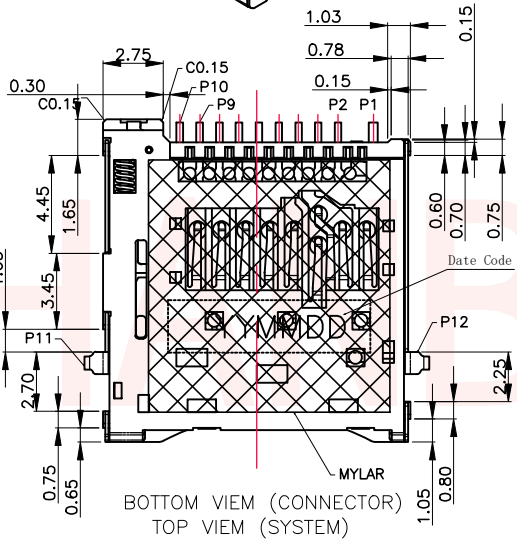
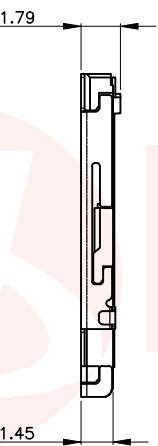
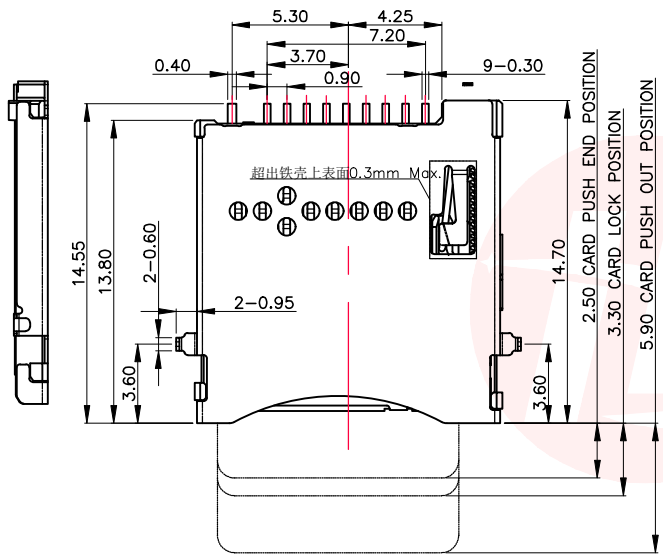
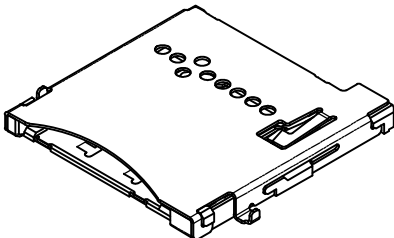
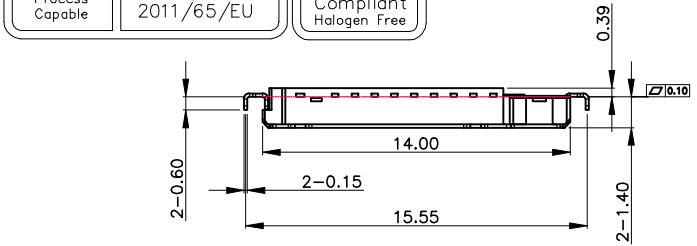




REV.	ECN NO OR DESCRIPTION	REVISED	DATE

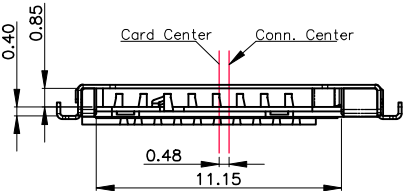


NOTE:
1.MATERIAL:
1-1 PLASTICS: HEAT RESISTANCE POLYMER, UL94V-0,COLOR:BLACK
1-2 CONTACT: COPPER ALLOY
1-3 SHELL: STAINLESS STEEL
2.PLATING:
2-1 CONTACT:
2-1-1: CONTACT AREA: Au 1u" PLATING OVER Ni.
2-1-2: SOLDER TAIL AREA: MATTE TIN 80u" MIN. OVER Ni.
30u" MIN
2-2 SHELL: SOLDERABILITY Ni PLATING OVER ALL
3.CONTACT AND TAIL COPLANARITY TO BE 0.10mm MAX.
4.PART MUST COMPLY TAI SOL HF WD-3-1-09I SOPECIFICATION
5.RECOMMENDING A METAL MORE THAN 0.10 THICK.
PLEASE CONFIRM SOLDILITY, IF USE A METAL MASK LESS THAN 0.10mm THICK.
6.PRODUCT PACKING: PLEASE REFER TO THE PACKING REGULATION

PAD AREA

Recommended P.C.B LAYOUT
BOTTOM VIEW(CONNECTOR) (TOLERANCE+/-0.05)
TOP VIEW(SYSTEM)

Pin No.	Pin Assignment
P1	MICRO SD CD
P2	MICRO SD DAT1
P3	MICRO SD DAT0
P4	MICRO SD VSS
P5	MICRO SD CLK
P6	MICRO SD VDD
P7	MICRO SD CMD
P8	MICRO SD CD/DAT3
P9	MICRO SD DAT2
P10	MICRO SD GND
P11	MICRO SD GND
P12	MICRO SD GND



Opening/Close of Switch

Card Detect Switch	Open	Close
Card Uninsertion	Open	
Card Half Insertion	Open	
Card Insertion		Close
N/O	Open	Close

UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD			
DECIMALS:	ANGLES:	TITLE	MICRO SD P-P SINK H175		
X :±0.35	X :±2°	DWN	xiong	PART NO. MR-1211-H175	
X.X :±0.25	X.X :±1°	CHKD	lee	SCALE:1:1	UNIT: mm
X.XX :±0.10		APVD	wang	SIZE: A4	SHEET:1OF 1
					REV: A4
				CUSTOMER COPY	